



Innovative **Technology**
for a **Connected** World

86750 Nickel/Copper Fabric Tape



NI/CU POLYESTER CONDUCTIVE FABRIC TAPE

Laird Technologies' Conductive Fabric Tape 86750 product is made of metallized fabric (polyester Ni/Cu) coated with a pressure sensitive adhesive. These products can be used as EMI/RFI shielding and grounding tape, which would meet market requirements.

FEATURES

- RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Low surface resistivity of $< 0.03 \Omega/\square$ provides excellent conductivity
- Shielding effectiveness of 70 dB across a wide spectrum of frequencies

MARKETS

- Cabinet applications
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Laptop computers



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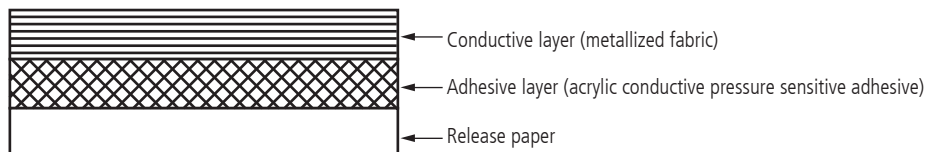
Asia: +86.755.2714.1166

www.lairdtech.com

Item	Unit	Value	Test Method
Thickness	mm	0.075 mm ± 0.015	-
Peel Adhesion	Kgf / 25 mm	>0.9	PSTC 101*
Shear Adhesion			ASTM D4935
at R.T.	Hrs	>72	PSTC 107#
at 80°C	Hrs	>3	PSTC 107#
Tensile Strength	Kgf / 25 mm	>7.5	
Operation Temperature	°C	0-80	
Surface Resistivity (Fabric Side)	Ω/□	<0.03	ASTM F390
Z-axial Resistance	Ω	<0.03	
Shielding Effectiveness ⁺			ASTM D4935
at 100 MHz	dB	70	
at 1 GHz	dB	75	
Package Dimensions (Max. Width: 1000 mm)	M	W: Dimension by Customer Spec L: Standard Length of 20 M	
Shelf Life (Under 23°C/65% R.H.)		Six Months	

*:Test Method A, dwell time 30 min. #:Contact area 25 mm by 25 mm +:Typical value

COMPOSITION OF PRODUCT



APPLICATION TECHNIQUES

- Bond strength is dependent upon the amount of adhesive-to-surface contact developed. Firm application pressure develops better adhesive contact & thus improves bond strength.
- To obtain optimum adhesion, the bonding surfaces must be clean, dry and well unified. A typical surface cleaning solvent is isopropyl alcohol. Use proper safety precautions for handling solvents.
- Ideal tape application temperature range is 21°C to 38°C. Initial tape application to surfaces at temperatures below 10°C is not recommended because the adhesive becomes too firm to adhere readily. However, once properly applied, low temperature holding is generally satisfactory.